

Appln. No. 09/920,192

Attorney Docket No. 10541-609

I. Amendments to th Specification

Please replace the Abstract paragraph with the following amended paragraph:

ABSTRACT

~~A method for producing an~~ An electronic circuit assembly (e.g., a circuit board) ~~from having~~ an etched tri-metal-layer structure which provides air bridge crossovers and specially designed bumps etched from a middle layer of the tri-metal-layer structure. The bumps are formed at particular circuit locations in order to provide interconnects for (1) heavy wirebonding, (2) fine wirebonding, or (3) direct chip attachment; or, to provide (4) lifters for assuring a minimum solder joint standoff height or (5) barriers for retarding solder joint crack propagation.